

1.0 INTRODUCTION

This drawing describes the requirements for procuring the unpackaged integrated circuit die used in the manufacture of part number ICL8212 which is a programmable voltage reference. All changes and/or substitutions to the procured parts are subject to prior approval by ICI. This specification is to be used with GEN-008, General Specification for Integrated Circuit Dice.

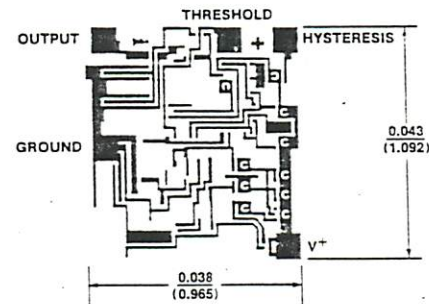
2.0 APPLICABLE DOCUMENTS

GEN-008 General Specification for Integrated Circuit Dice

3.0 REQUIREMENTS

3.1 Mechanical/Physical Characteristics

Each die shall be configured as shown in Figure 1.
 Each die shall be electrically connected as shown in Figure 2.




DIE IS PASSIVATED WITH A DEPOSITED OXIDE. BONDING PAD OXIDE WINDOWS ARE 3.6 x 3.6 MILS SQUARE.

NOTES:

1. Mfrs. Intersil
2. Die size .043 x .038 ± .005
3. Die thickness .008 ± .003

FIGURE 1
 DIE CONFIGURATION

99126-003 A

 Integrated Circuits Incorporated 10301 WILLOWS ROAD, REDMOND, WA 98052	SIZE	FSCM NO.	DRAWING NO.	REV
	A	50821	84669	A
SCALE			SHEET 2 OF 4	